



CALL FOR PAPERS

IMPORTANT DATES

Paper Submission Deadlines

February 15, 2026

Option B: Submit to IEEE Sensors Letters

March 9, 2026

Option A: Submit to IEEE FLEPS 2026
Proceedings

April 20, 2026

Notification of Acceptance

May 11, 2026

Final Manuscript Submission Deadline

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The IEEE International Conference on Flexible, Printable Sensors and Systems (FLEPS 2026) will be held in Atlanta, Georgia, USA.

IEEE FLEPS 2026 is intended to provide a forum for research scientists, engineers, and practitioners throughout the world to present their latest research findings, ideas, and applications in the area of Flexible and Printable Sensors and Systems.

TOPICS OF INTEREST

- » Organic/Inorganic Electronics and Sensors
- » Materials and Design for Flexible, Stretchable, and Printed Systems
- » Advanced Manufacturing Techniques
- » High-throughput Printable Electronics
- » Hybrid Systems and Heterogeneous Integration
- » Stretchable/Shrinkable Sensors and Electronics
- » Wearable and Implantable Systems
- » Degradable/Reusable Sensors and Systems
- » Printed Large-Area Sensors and Systems
- » Active and Passive Components (e.g. actuators, printed energy devices, smart labels, RFID etc.)
- » Emerging applications of Flexible Electronics in AI, Robotics, Cognitive Systems, IoT, smart cities etc.
- » Reliability, Simulation and Modelling
- » Electronics for Sustainability
- » Standards for Flexible and Stretchable Electronics

For further information, contact **Sara Diffenbach** at Conference Catalysts, LLC.

